

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (currently amended): A testing apparatus comprising:

 a base controller comprising a plurality of first connectors that are connectable to a tester;
 a plurality of test controllers, each said test controller electrically connected to
~~comprising~~ a plurality of second connectors that are electrically connectable to an electronic
device; and
 wireless means for communicating test data wirelessly between said base controller and
said test controllers.

Claim 2 (canceled)

Claim 3 (previously amended): The apparatus of claim 1, wherein at least a portion of one of
said test controllers is disposed on said electronic device.

Claim 4 (currently amended): ~~A testing apparatus comprising:~~

~~—— a base controller comprising a plurality of first connectors that are connectable to a tester;~~
~~—— a plurality of a test controllers comprising a plurality of second connectors that are~~
~~connectable to an electronic device;~~
~~—— wireless means for communicating test data wirelessly between said base controller and~~
~~said test controller; and~~ The apparatus of claim 1 further comprising
 an enclosure that is sealable, at least one of said base controller, test controller, or
wireless means disposed within said enclosure.

Claim 5 (original): The apparatus of claim 1, wherein said electronic device comprises a
semiconductor die.

Claim 6 (previously amended): The apparatus of claim 1 further comprising a plurality of said electronic devices, and wherein each said electronic device comprises a semiconductor die, and said dies compose an unsingulated semiconductor wafer.

Claim 7 (previously amended): The apparatus of claim 1, wherein said wireless means comprises a first transceiver electrically connected to said test controller and second transceivers electrically connected to said base controller.

Claim 8 (currently amended): ~~A testing apparatus comprising:~~
~~—— a base controller comprising a plurality of first connectors that are connectable to a tester;~~
~~—— a test controller comprising a plurality of second connectors that are connectable to an electronic device; and~~
~~—— wireless means for communicating test data wirelessly between said base controller and said test controller;~~ The apparatus of claim 1, wherein said second connectors comprise a plurality of probes, each disposed to contact a terminal of said electronic device.

Claim 9 (original): The apparatus of claim 1, wherein said test data includes at least one of test vectors or test commands.

Claims 10-13 (canceled)

Claim 14 (currently amended): A test system comprising:

a tester;

a test station;

a communications link between said tester and said test station; and

a substrate disposed in said test station, said substrate comprising:

a base controller in communication with said communications link;

a plurality of test controllers each electrically connected to ~~comprising~~ a plurality of connectors that are electrically connectable to one of a plurality of electronic devices to be tested; and

wireless means for communicating test data wirelessly between said base controller and said plurality of test controllers.

Claim 15 (original): The test system of claim 14, wherein at least a portion of one of said test controllers is disposed on one of said electronic devices.

Claim 16 (previously amended): The test system of claim 14, wherein said connectors comprise a plurality of probes, each disposed to contact a terminal of one of said electronic devices.

Claim 17 (original): The test system of claim 14 further comprising a plurality of said testers, each in communication with said communications link.

Claim 18 (original): The test system of claim 17 further comprising a plurality of said test stations, each in communication with said communications link.

Claim 19 (original): The test system of claim 18, wherein said electronic devices are semiconductor dies.

Claim 20 (original): The test system of claim 19, wherein said semiconductor dies compose an unsingulated semiconductor wafer.

Claim 21 (original): The test system of claim 14, wherein said test data includes at least one of test vectors or test commands.

Claim 22 (original): The test system of claim 14 further comprising a cassette in which said substrate is disposed.

Claim 23 (original): The test system of claim 22, wherein said cassette is hermetically sealable.

Claim 24 (original): The test system of claim 14, wherein said substrate composes a probe card.

Claims 25-39 (canceled)

Claim 40 (New): The apparatus of claim 1, wherein said base controller comprises processing circuitry.

Claim 41 (New): The apparatus of claim 40, wherein said processing circuitry comprises a microprocessor.

Claim 42 (New): The apparatus of claim 1, wherein said base controller receives said test data and controls transmission of said test data through said wireless means to a multiplicity of said test controllers.

Claim 43 (New): The apparatus of claim 1, wherein each said test controller comprises processing circuitry.

Claim 44 (New): The apparatus of claim 43, wherein said processing circuitry comprises a microprocessor.

Claim 45 (New): The apparatus of claim 1, wherein each said test controller controls writing of test data to at least one electronic device to be tested.

Claim 46 (New): The apparatus of claim 45, wherein each said test controller further controls reading of response data from said at least one electronic device.

Claim 47 (New): The apparatus of claim 46, wherein each said test controller further analyzes said response data.